

The Central Outer Tracker for Run II at CDF

David Ambrose
University of Pennsylvania
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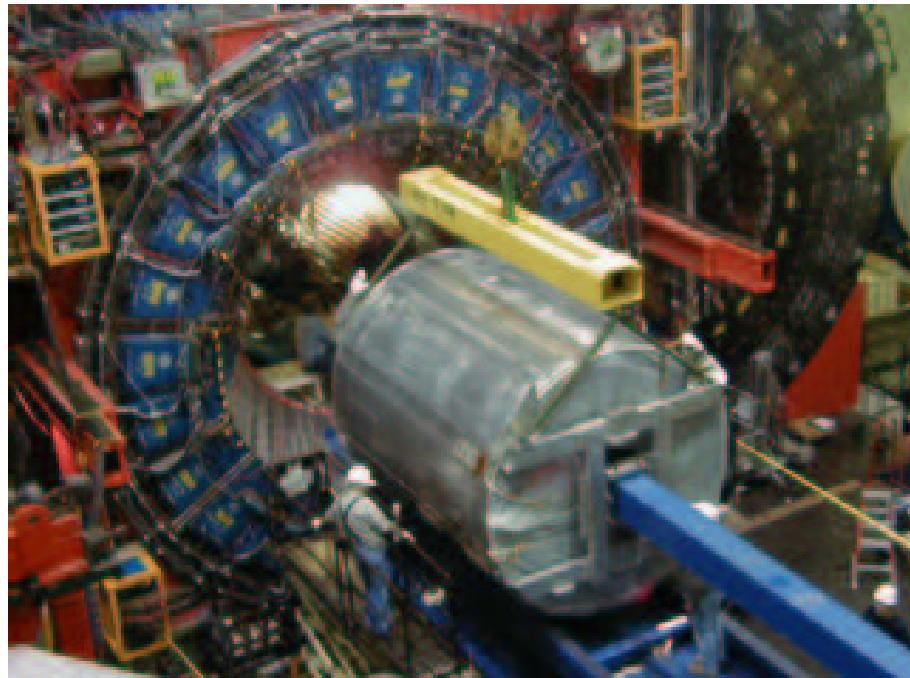
Outline:

- ▷ overview
- ▷ design for Run II upgrade
- ▷ components and construction
- ▷ Run II performance and outlook

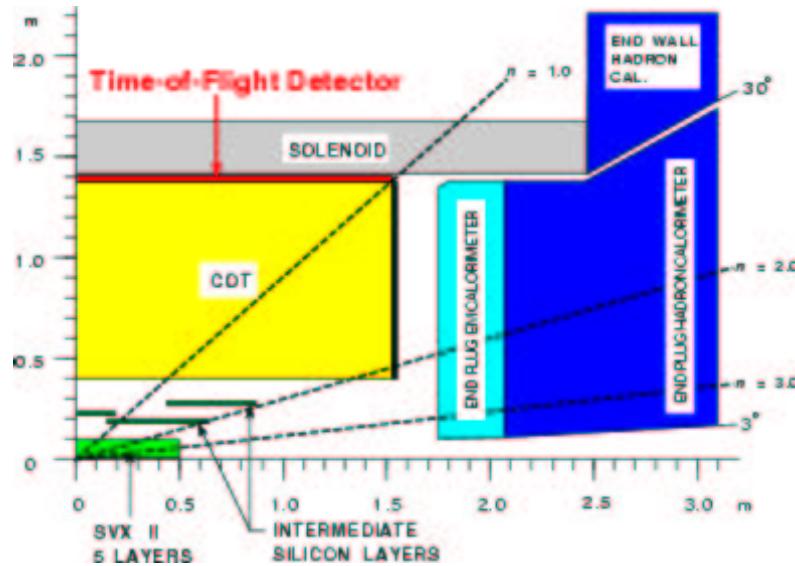
COT Collaboration

T. Affolder, D. Allspach, D. Ambrose, J. Bialek, W. Bokhari, M. Brozovic, M. Binkley,
K. Burkett, A. Byon-Wagner, F. Cogswell, N. Dressnandt, Z. Feng, M. Franklin,
L. Galtieri, D. W. Gerdes, J. Greenwood, V. Guarino, J. Guimaraes da Costa, R. Haggerty,
C. Hall, J. Heinrich, A. Holloway, T. Jacobi, K. Kephart, D. Khazins, Y. K. Kim, M. Kirby,
W. Kononenko, A. V. Kotwal, J. Kraus, T. M. Liss, N. Lockyer, R. Madrak, T. Miao,
A. Mukherjee, C. Neu, M. Newcomer, J. M. Niczyporuk, L. Nodulman, W. Orejudous,
T. J. Phillips, K. T. Pitts, W. Reigler, R. Richards, C. Rivetta, W. J. Robertson, R. Roser,
L. Sadler, R. Sandberg, S. Sansone, R. Schmitt, K. Schultz, D. Shuman, R. Silva, P. Singh,
R. Snihur, P. Tamburello, J. Taylor, R. Thurman-Keup, D. Tousignant, F. Ukegawa,
R. Van Berg, G. Veramendi, T. Vickey, J. Wacker, R. L. Wagner, R. Weidenbach,
W. C. Wester III, H. H. Williams, P. Wilson, P. Wittich, A. Yagil, I. Yu, S. Yu, J. C. Yun

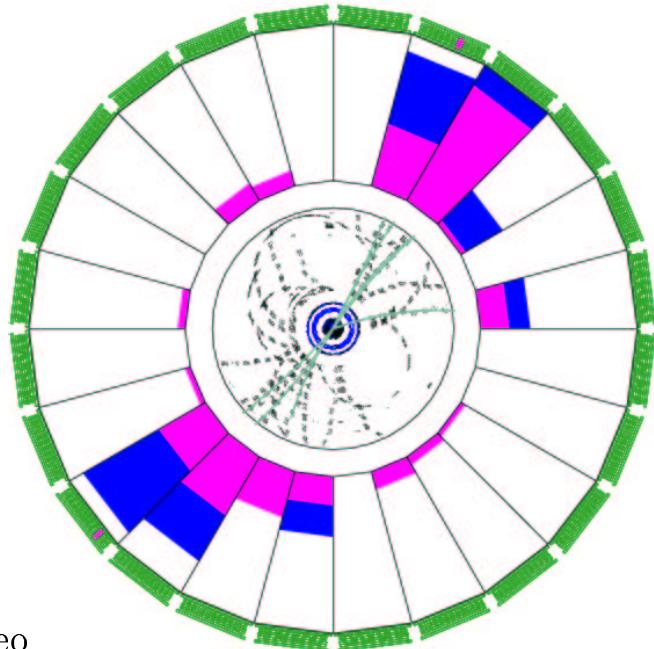
*Argonne National Laboratory, Duke University,
Fermi National Accelerator Laboratory, Harvard University,
University of Illinois, Johns Hopkins University,
Lawrence Berkeley National Laboratory, University of Michigan,
Michigan State University, University of Pennsylvania,
University College London,*



Central Outer Tracker: Overview



- ▷ large, open-cell cyl. drift chamber
- ▷ within 1.4 T solenoid magnet
- ▷ active region:
 - ⇒ 310 cm along beamline
 - ⇒ 43 cm inner radius
 - ⇒ 132 cm outer radius
- ▷ precision $r\phi$ tracking,
momentum measurement
- ▷ rz tracking with small-angle stereo
- ▷ fast hit signals for Level 1 track triggers



Design for Run II Upgrade

- ▷ primary goal:
reproduce Run I CTC performance for Run II luminosity
- ▷ primary design constraint:
 $100 \text{ ns maximum drift time} \implies 1/4 \text{ cell size of CTC}$

	Run I	Run II	Run IIb
bunches	6	36	108
spacing	3500 ns	396 ns	132 ns

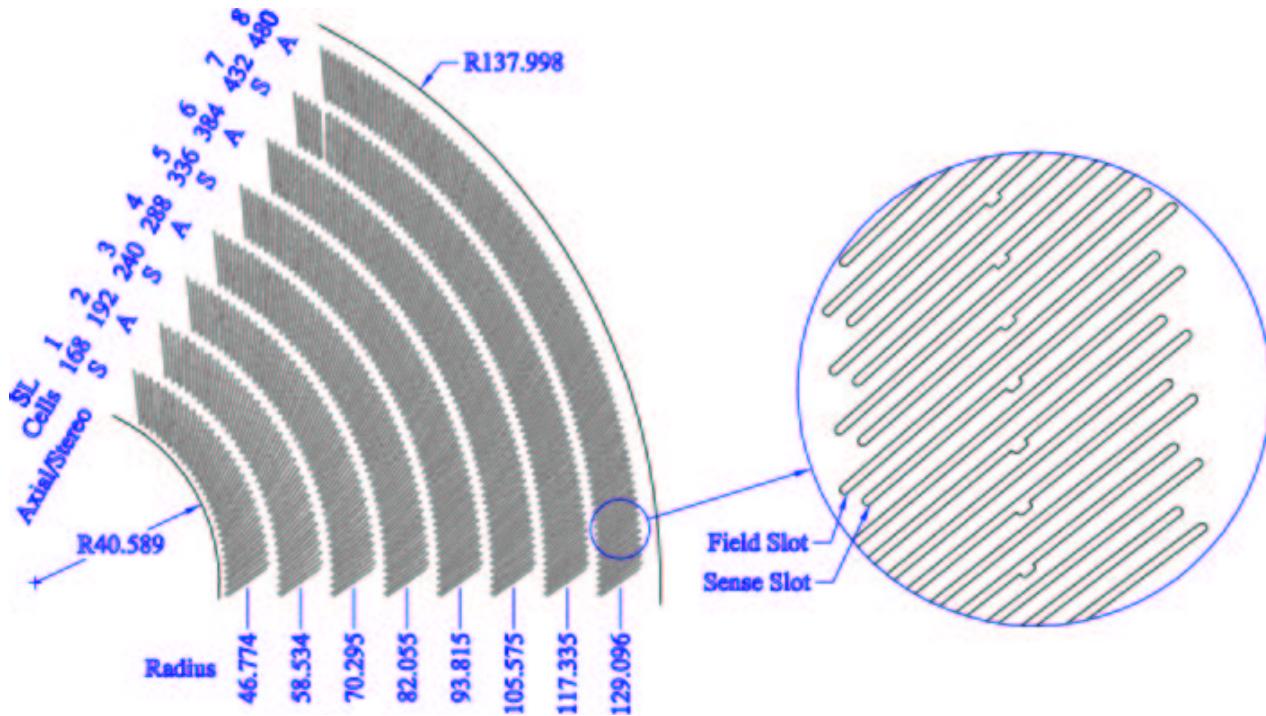
- ▷ more bunches, smaller cell size give similar occupancies at:

$$\mathcal{L} = 1.6 \times 10^{32} \text{ cm}^{-2}\text{s}^{-1} \text{ (36 bunch)}$$

$$\mathcal{L} = 4.0 \times 10^{32} \text{ cm}^{-2}\text{s}^{-1} \text{ (108 bunch)}$$
- ▷ cathode field sheets allow smaller cell (higher field, reduced mass)
- ▷ improve stereo capability over Run I CTC

	Run I CTC	Run II [IIb] COT
drift gas	50:50 Ar/Et + Ethyl	50:50 Ar/Et + Isopropyl [50:35:15 Ar/Et/CF ₄ + Iso]
max drift distance	3.6 cm	0.88 cm
max drift time	706 ns	177 ns [100 ns]
Lorentz angle (cell tilt)	$\sim 45^\circ$ (45°)	$\sim 31^\circ$ (35°) [$\sim 31^\circ$ (35°)]
drift field	$\sim 1.3 \text{ kV/cm}$	1.9 kV/cm [2.1–2.4 kV/cm]
radiation lengths	1.7%	1.7%
sense-wire layers (SL)	84 (9)	96 (8)
sense-wires/SL	12 (odd SL), 6 (even SL)	12 (all SL)
stereo-angle/SL	$\pm 3^\circ$ (even SL)	$\pm 2^\circ$ (odd SL)
total sense-wires	6156	30240
total wires	36504	63000
endplate load	25 tons	40 tons

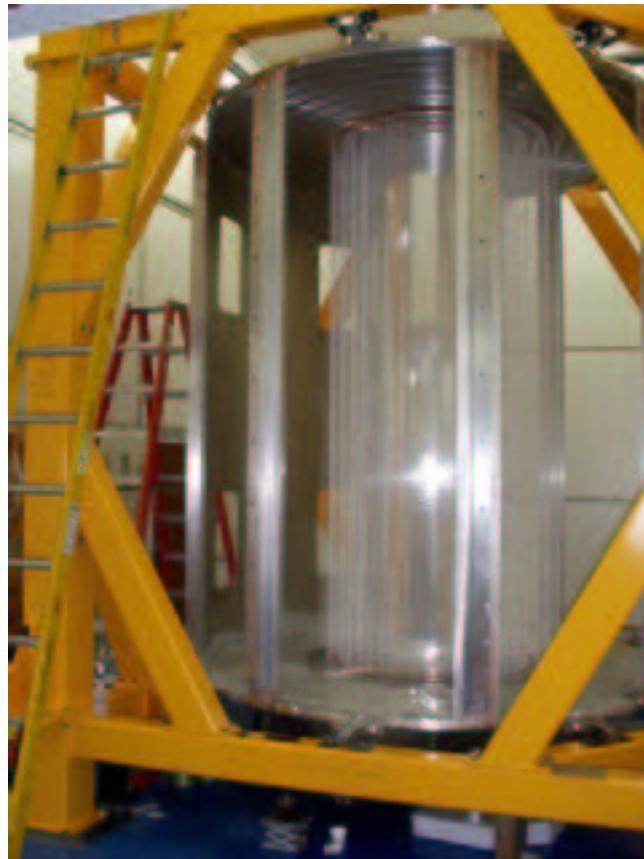
COT Endplate



- ▷ composed of 6061-T651 aluminum,
4.128 cm thick, 409 kg
- ▷ machined with end mill due to radius
- ▷ wire planes and field sheets positioned
with machined slots
- ▷ # of precision edges kept small
(one surface per slot, one edge per notch)
- ▷ 2°-stereo by stepping 6 cells (12 slots)
- ▷ endplate deflection under load tested
with vacuum, 0.538 cm at maximum

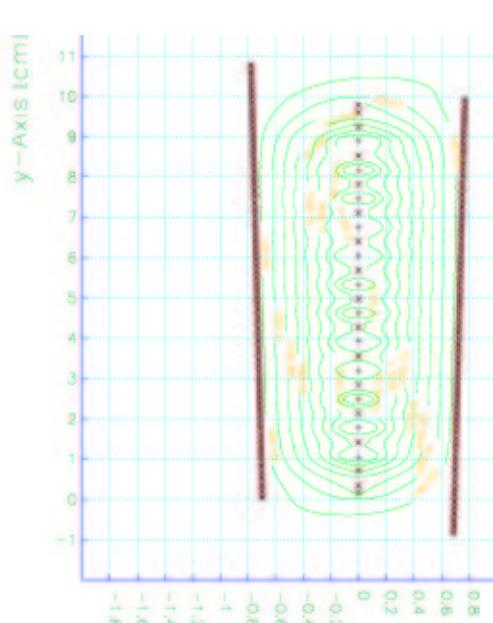
SL	Cells	Sense Wires
1	168	2016
2	192	2304
3	240	2880
4	288	3456
5	336	4032
6	384	4608
7	432	5184
8	480	5760
	2520	30240

COT “Can” Assembly

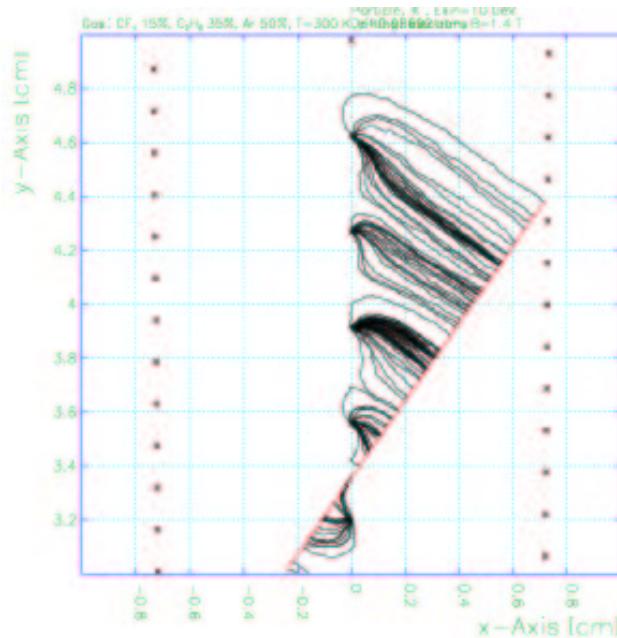


- ▷ inner cylinder:
 - ⇒ 0.251 cm thick carbon fiber / epoxy composite (0.99% rad length)
 - ⇒ 25.4 μ m outer aluminum shielding
 - ⇒ carries 14,000 kg of load
- ▷ outer cylinder:
 - ⇒ 8 ϕ -sections of 0.635 cm thick 6061-T651 aluminum (cover plates)
 - ⇒ precision staves set z -distance between endplates
 - ⇒ hatches allow access during stringing
 - ⇒ carries 22,000 kg of load
- ▷ “Can” assembled vertically with alignment fixture
- ▷ slots pre-strung for pulling wire planes, field sheets

COT Wire Cell Design



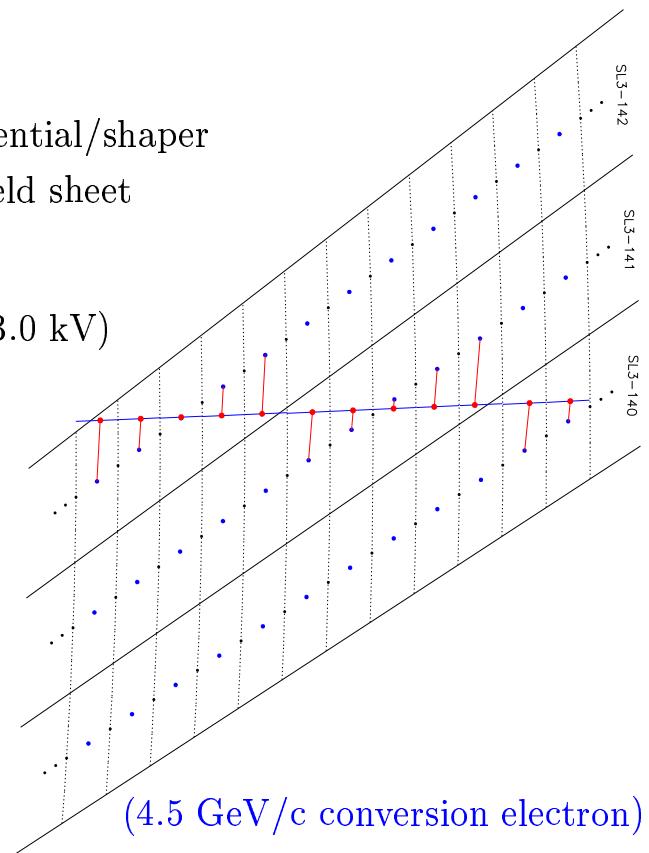
(equipotential contours)



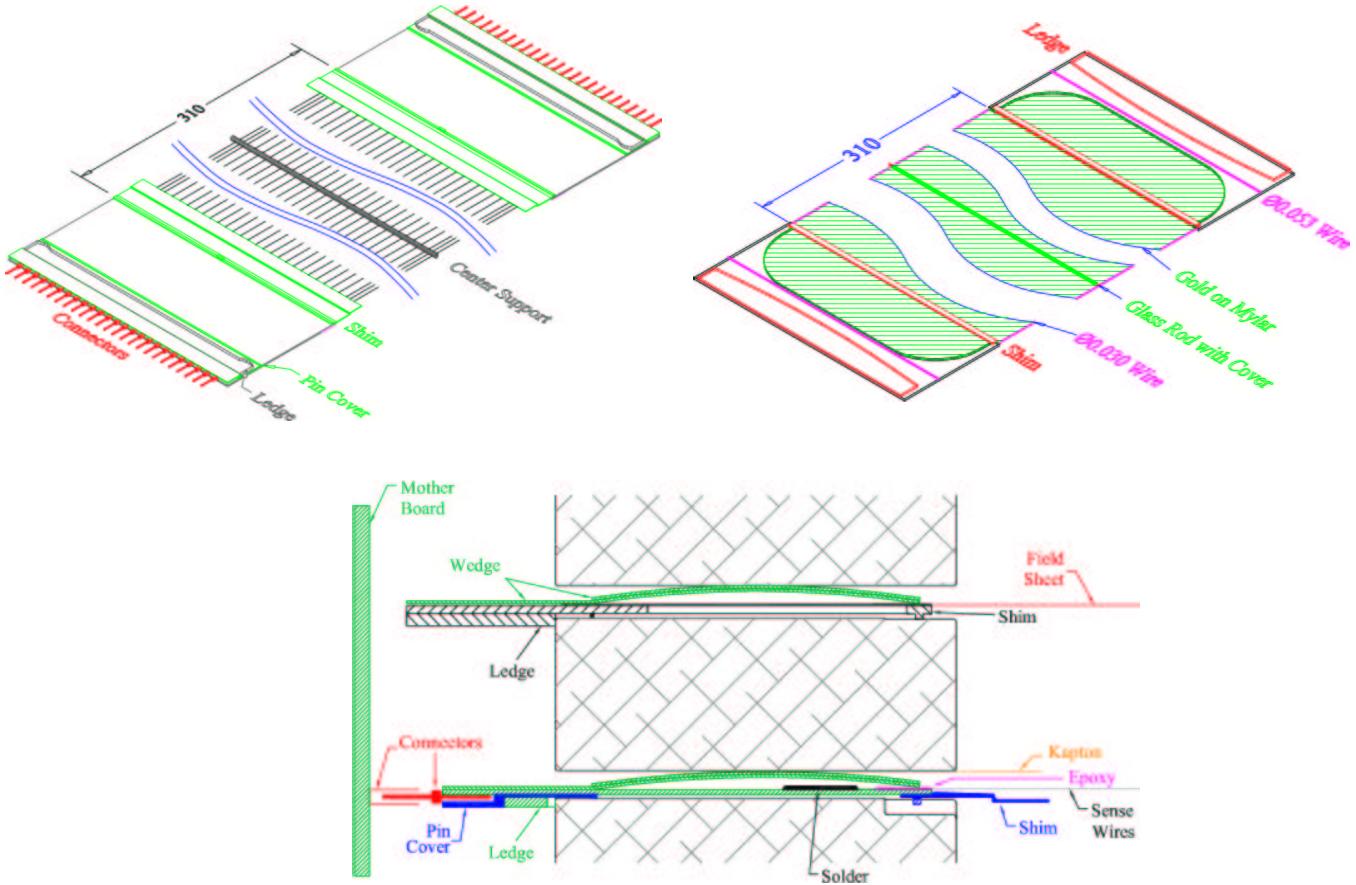
(simulated drift trajectories)

- ▷ “super-cell”:
 - ⇒ wire plane of 12 sense, 15 potential/shaper
 - ⇒ separated by cathode plane field sheet

- ▷ cell electrostatics:
 - ⇒ incremented HV for sense (~ 3.0 kV) and potential (~ 2.2 kV)
 - ⇒ shaper wires (at higher HV) reduce edge effects
 - ⇒ produces uniform drift field ~ 1.9 kV/cm, $\sim 2 \times 10^4$ gain
 - ⇒ Lorentz angle near 35° (cell tilt), creates drift trajectory perpendicular to radial track



COT Wireplanes and Fieldsheets

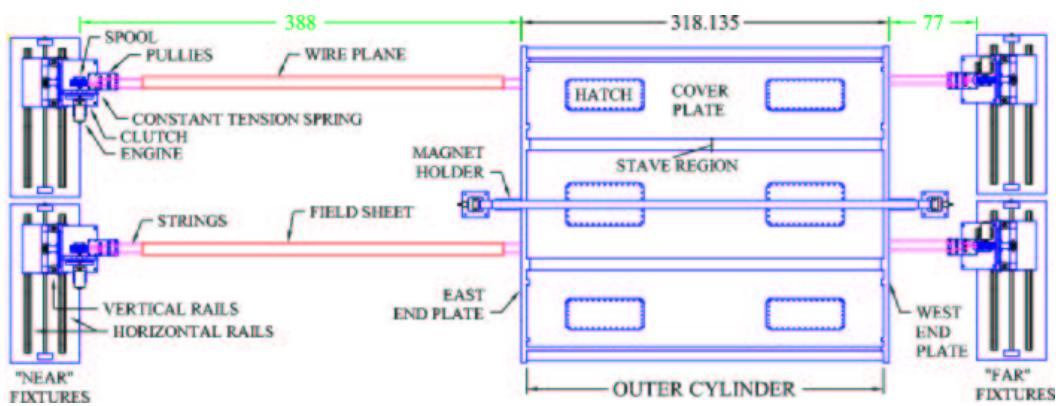
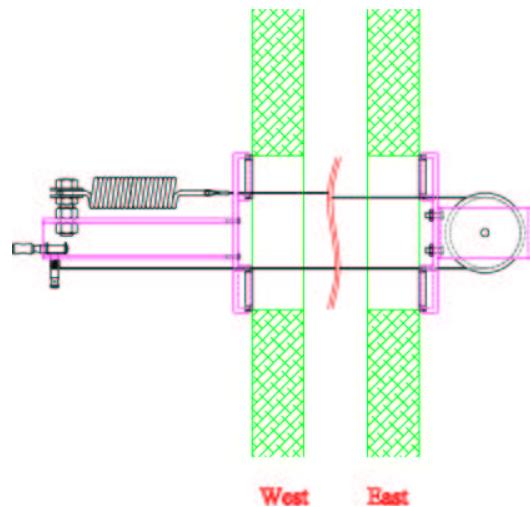


- ▷ wire planes:
 - ⇒ 40 μm diameter gold plated tungsten for all wires
 - ⇒ fiberglass center support ($\sim 12 \text{ mg}$) reduces electrostatic repulsion
 - ⇒ assembled with winding machine, wires attached to G10 end board
 - ⇒ tested for tension and HV (with Sr^{90} source) before installation
- ▷ field sheets:
 - ⇒ gold vapor deposited on 6.35 μm Mylar, aluminum end boards
 - ⇒ 305 μm parabolic SS edge wires to prevent ripple
 - ⇒ 2.4 mm diameter glass tube center support reduces deflection
- ▷ mounted in slots with end board ledges, precision shims, G10 wedges

Wireplane and Fieldsheet Installation

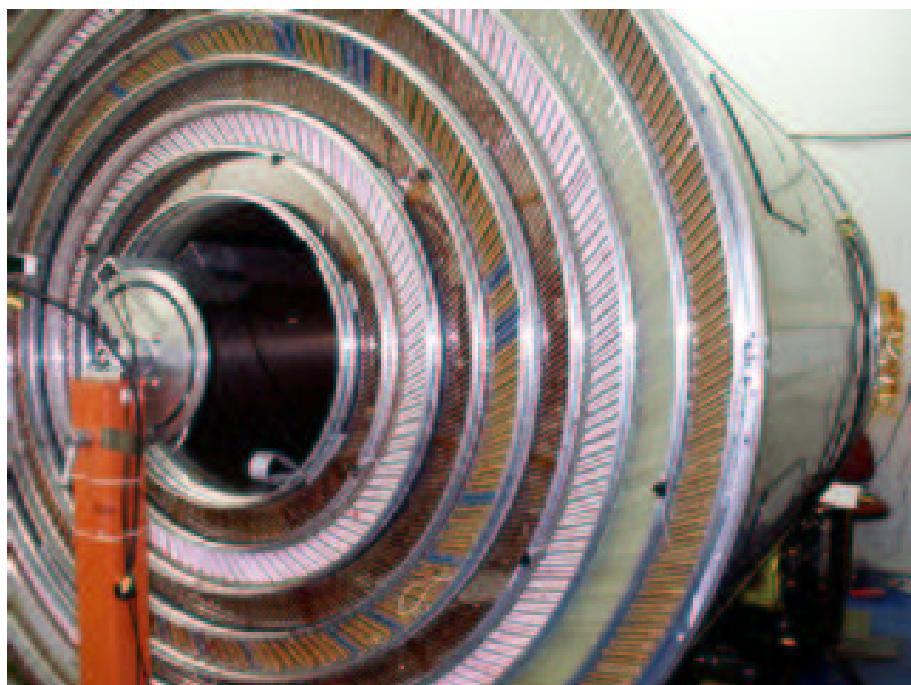
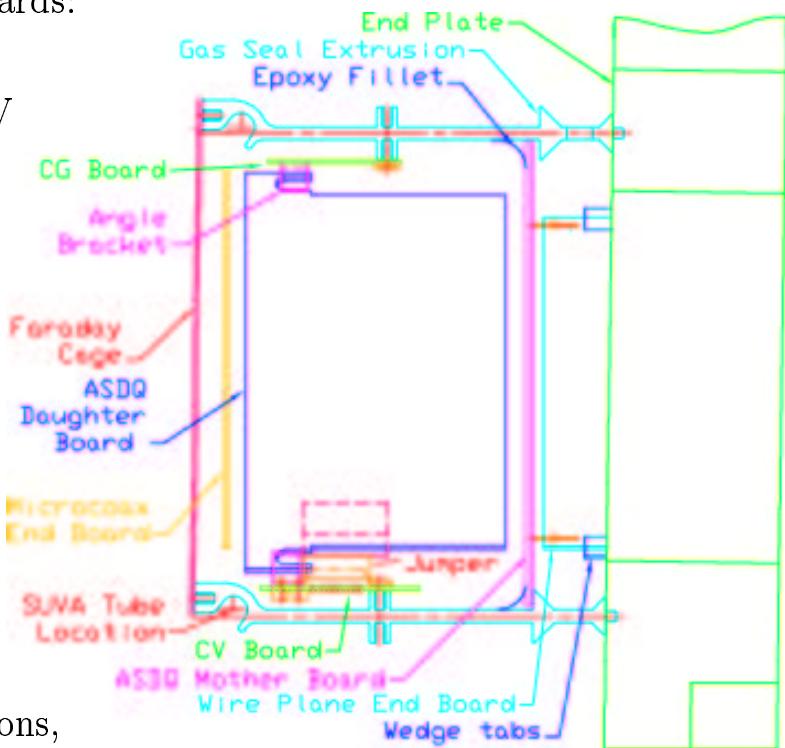


- ▶ chamber placed on rotating fixture
 - ▶ end plates pre-tensioned with piano wire, tuner
 - ▶ two stringing engines with controllable speed/tension
 - ▶ wire planes, field sheets pulled through with pre-strung lines

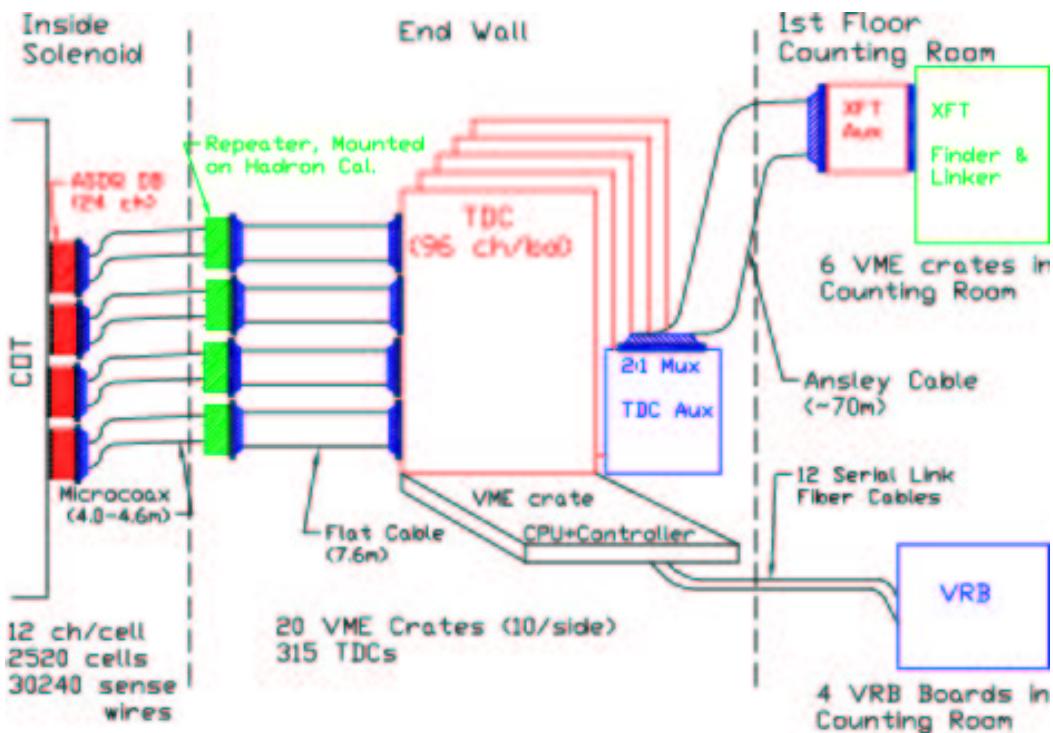


COT Gas Seal

- ▷ HV, readout G10 motherboards:
 - ⇒ form endplate gas seal
 - ⇒ feed-thru sockets for HV
 - ⇒ feed-thru plus blocking capacitors for readout
- ▷ aluminum extrusions:
 - ⇒ mounted on endplate
 - ⇒ base for motherboards
 - ⇒ grounded frame for HV, readout boards
 - ⇒ hold cooling lines and Faraday cages
- ▷ epoxy seals between extrusions, motherboards (leak rate ~1 SCFH)

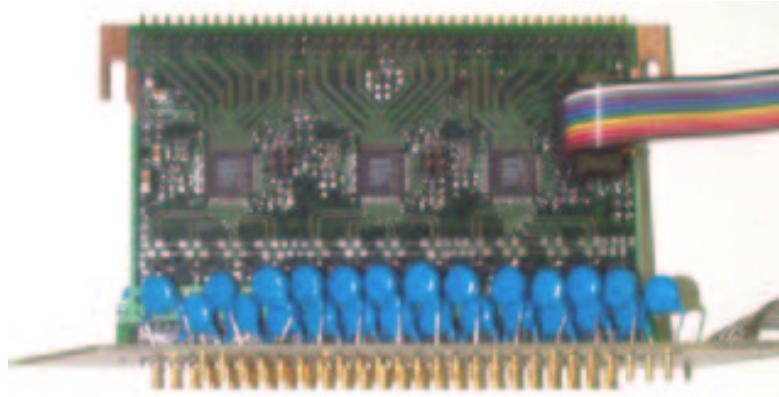


Front-end Electronics



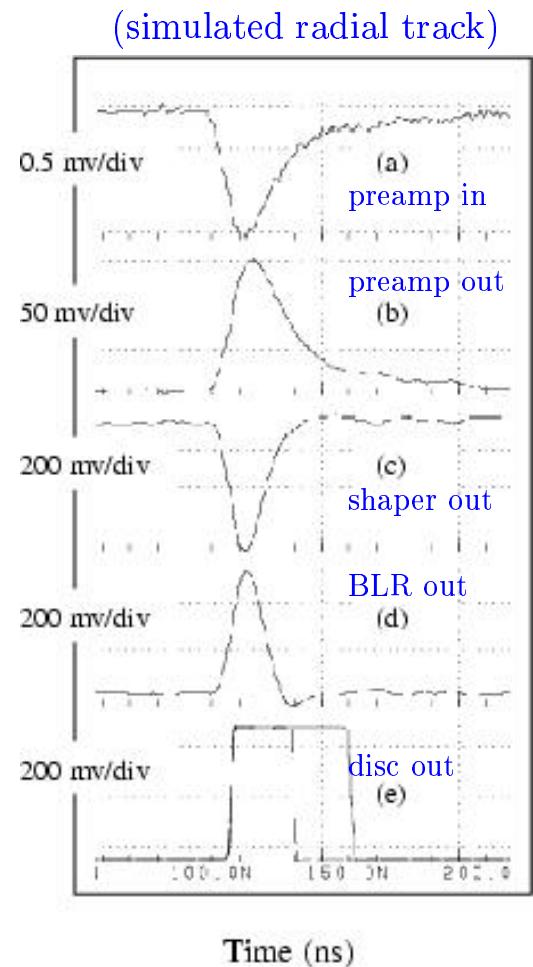
- ▷ alternating readout (SL1,4,5,8 on East; SL2,3,6,7 on West)
- ▷ signal processing, discrimination at chamber face with ASDQ boards
- ▷ differential signals exit solenoid via μ -coaxial cables
- ▷ “repeater” boards echo signals along flat cables to TDC crates
- ▷ TDC’s send multiplexed signals to Level 1 track trigger (XFT), then store signals in Level 1 pipeline and Level 2 buffer
- ▷ accepted event hits digitized, sent to VME readout boards

COT ASDQ



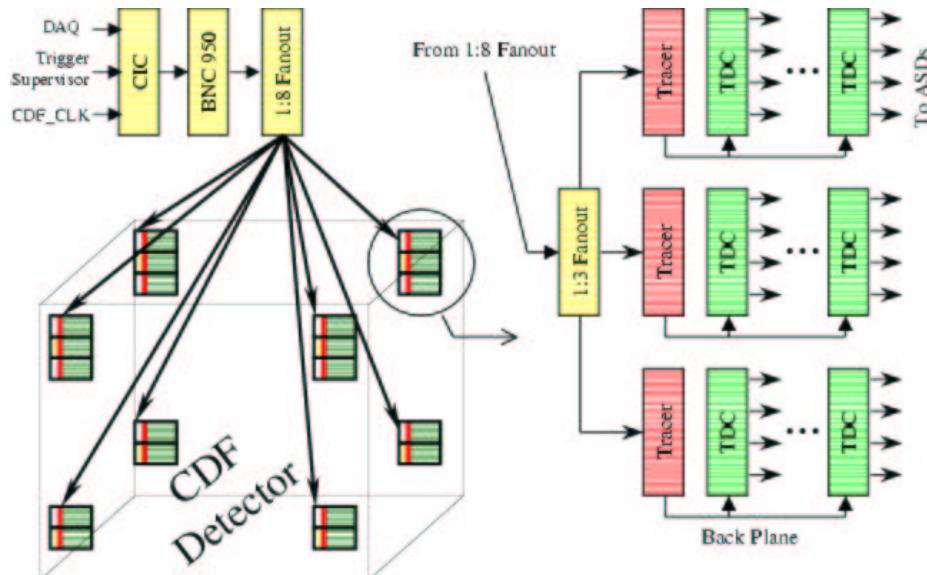
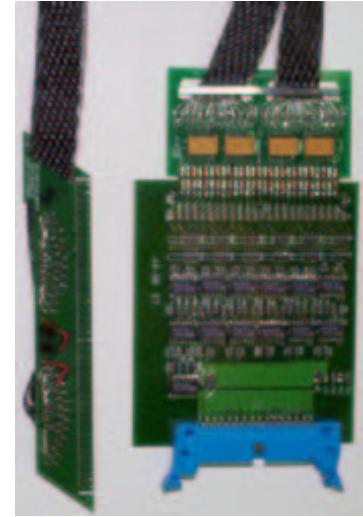
- ▷ 8-channel ASDQ chip:
 - ⇒ resistor and diode input protection
 - ⇒ preamplifier (pseudo-differential, 1.5 mv/fC gain)
 - ⇒ two-stage multipole shaping to cancel positive ion tail (optional attenuation for high gain operation)
 - ⇒ baseline restorer maintains uniform threshold at high rate
 - ⇒ analog monitor output after BLR
 - ⇒ discriminator with 2-10 fC threshold
 - ⇒ charge encoded in LVDS output width
 - ⇒ separate even/odd channel calibration input for channel t_0 , Q -to-width

- ▷ 24-channel ASDQ daughterboard:
 - ⇒ houses 3 ASDQ chips (handles 2 cells)
 - ⇒ added input protection, distributes power and control voltages, calibration signals

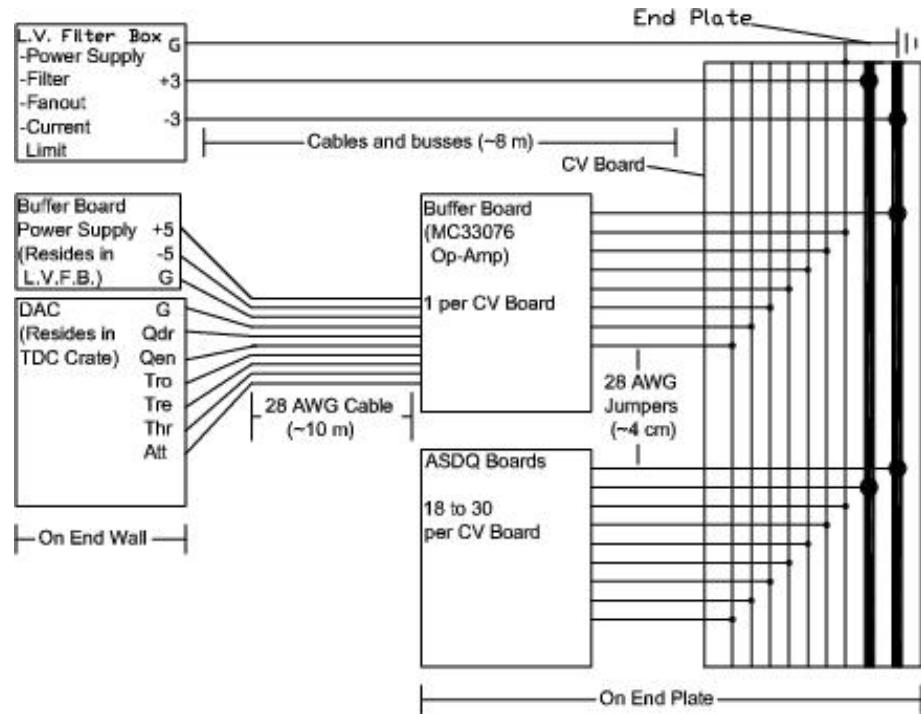


Repeater, TDC, and Calibration

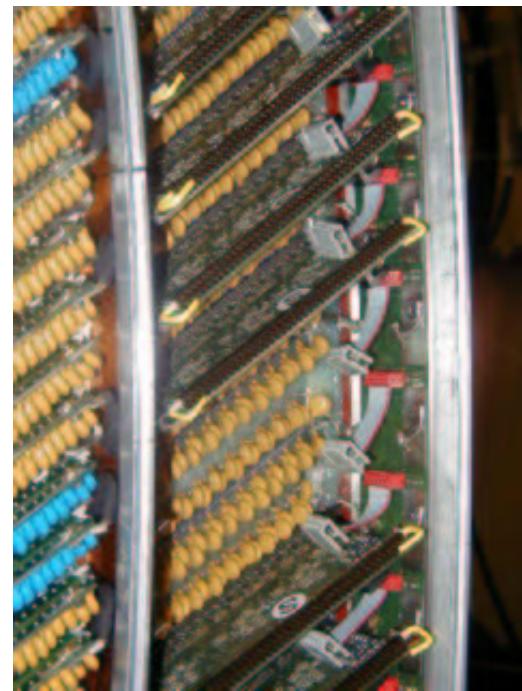
- ▷ “repeater” boards:
 - ⇒ provide ASDQ/TDC ground break
 - ⇒ amplify μ -coax signals onto larger conductor flat cables
 - ⇒ receive -3 V power from TDC via FC
- ▷ University of Michigan TDC96C TDC:
 - ⇒ also used for calorimeter, muon chambers
 - ⇒ JMC96 ASIC measures hit leading/trailing edges in 1 ns bins
 - ⇒ daughter board sends multiplexed axial hits (in two time bins) to eXtremely Fast Tracker (XFT) for Level 1 trigger
 - ⇒ hits enter 5.6 μ sec delay pipeline for L1, stored in L2 4-fold buffer
 - ⇒ JMC96 digitizes 2 μ sec of hits (8 max) into drift time, width
 - ⇒ DSP performs individual channel t_0 correction
- ▷ common calibration signal fanned-out to 20 crates of 315 TDC’s



Low Voltage Distribution

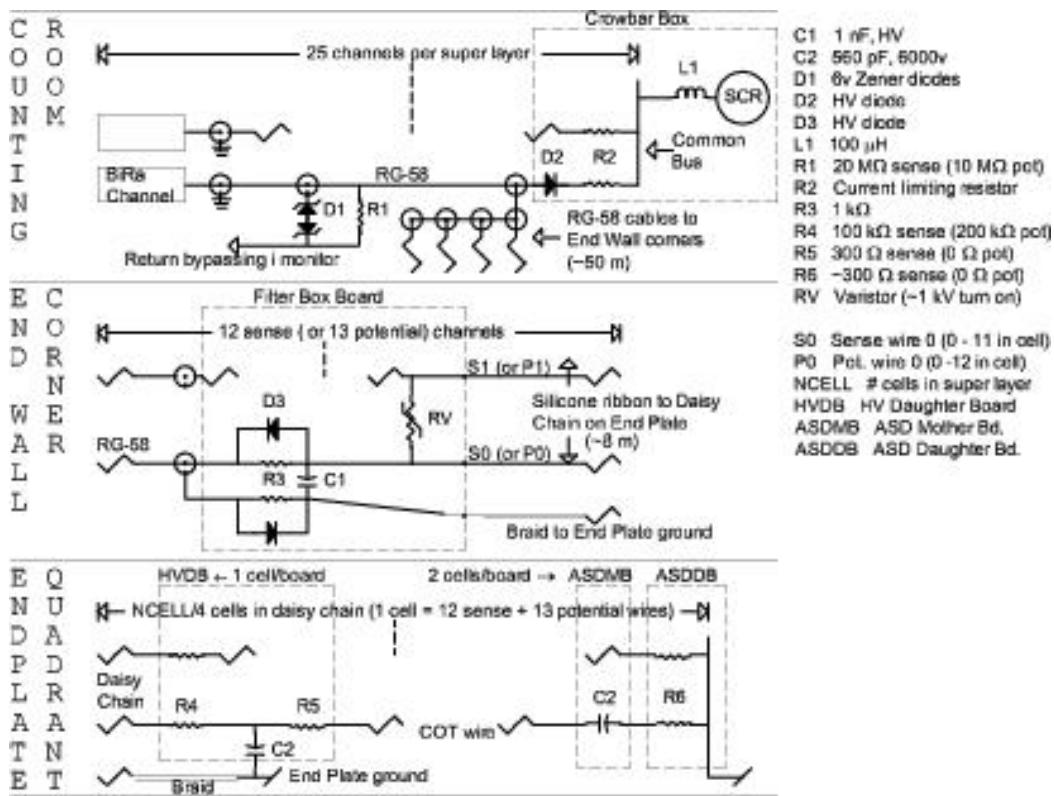
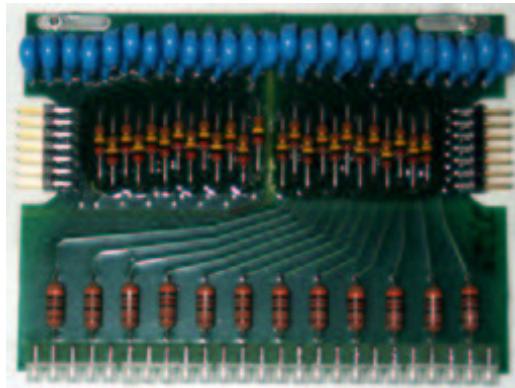


- ▷ low voltage filter boxes:
 - ⇒ provide ± 3 V ASDQ power for each SL/quadrant
 - ⇒ perform voltage regulation and filtering for switching noise
 - ⇒ distribute ASDQ control voltages (CV) from VME DAC modules
- ▷ ASDQ buffer boards drive CV's for each quadrant/octant:
 - ⇒ discriminator threshold
 - ⇒ attenuation/Q-enable switches
 - ⇒ output width control
 - ⇒ even/odd calibration reference
- ▷ circumferential voltage boards distribute power, CV along ϕ to ASDQ's

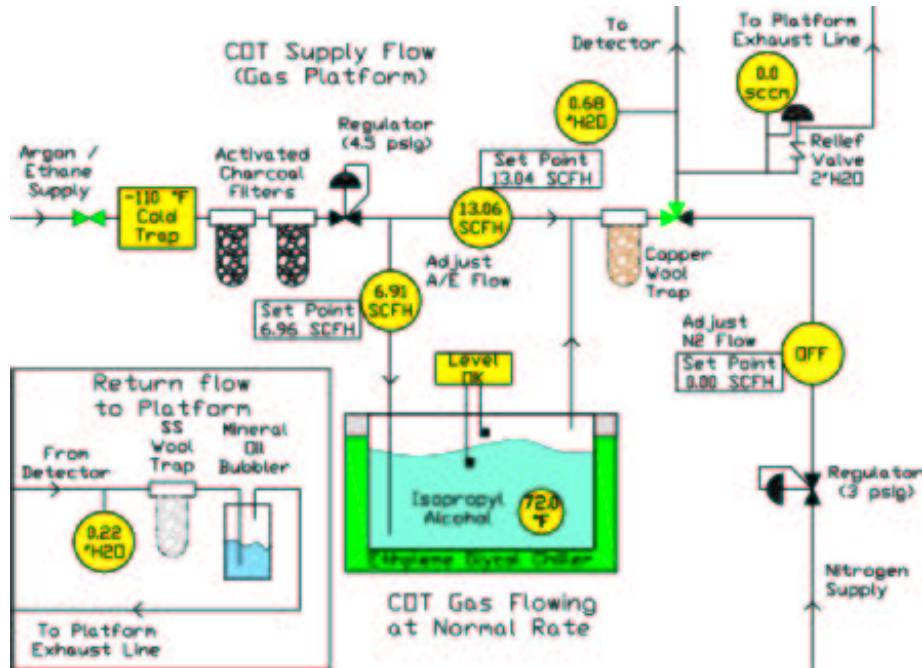


High Voltage Distribution

- ▷ HV for 200 sense/potential in 8 SL from BiRa VME 4877 crates
- ▷ HV crowbar boxes prevent multiple discharge during trips, fan-out HV to quadrants
- ▷ RG58 cables carry HV to endwall filter boxes with diode protection
- ▷ HV traverses silicone ribbon cable to endplate daisy chain
- ▷ HV daughter boards distribute voltage to wire plane end boards, provide sense wire termination



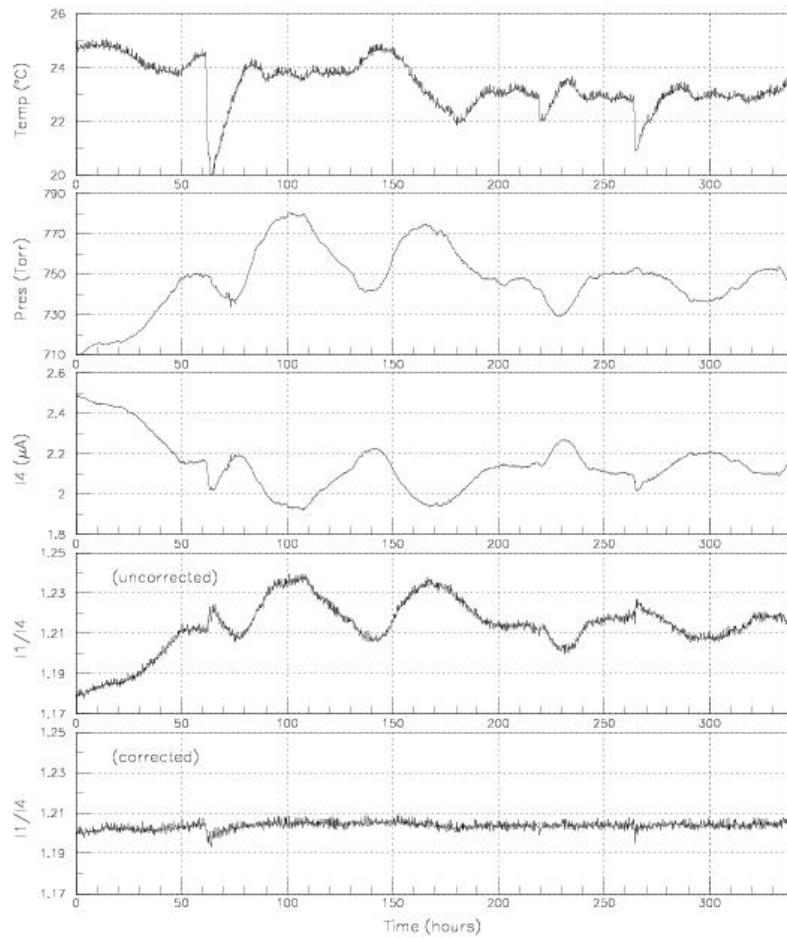
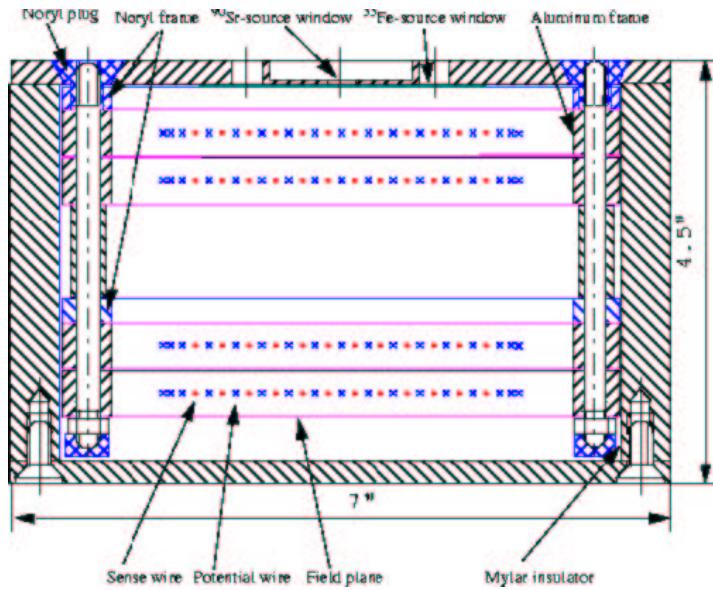
Drift Gas System



- ▷ -80°C cold trap (using liquid nitrogen) and activated charcoal filters remove impurities from Ar/Et supply
- ▷ 1/3 of supply sent through isopropyl alcohol bubbler at 22°C (for 1.7% alcohol concentration) to reduce aging effects
- ▷ heated copper wool trap removes aerosols from bubbler
- ▷ stainless steel tubing delivers Ar/Et to chamber face
- ▷ nitrogen purge tents over endplate prevent flammable gas buildup, maintain low humidity for electronics

Chamber Monitoring and Aging

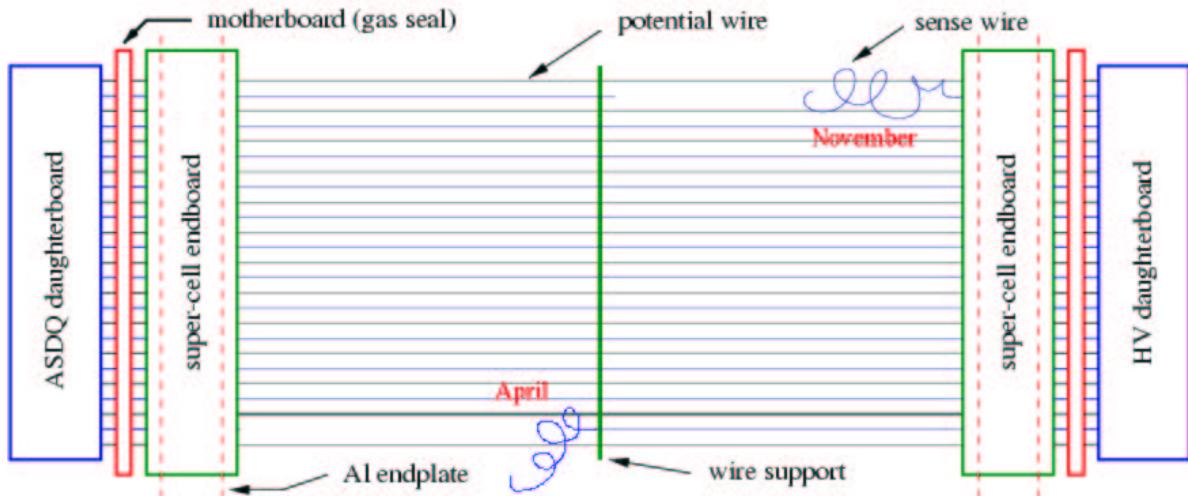
- ▷ gas monitor chambers sample drift gas at several points
- ▷ contain four 12 cm wire planes under HV with Sr^{90} source
- ▷ drop in gain due to aging measured from wire currents
- ▷ use ratio of currents to remove T/P dependence
- ▷ current aging measurement: $< 5\%/\text{C}/\text{cm}$



COT Run II Operation

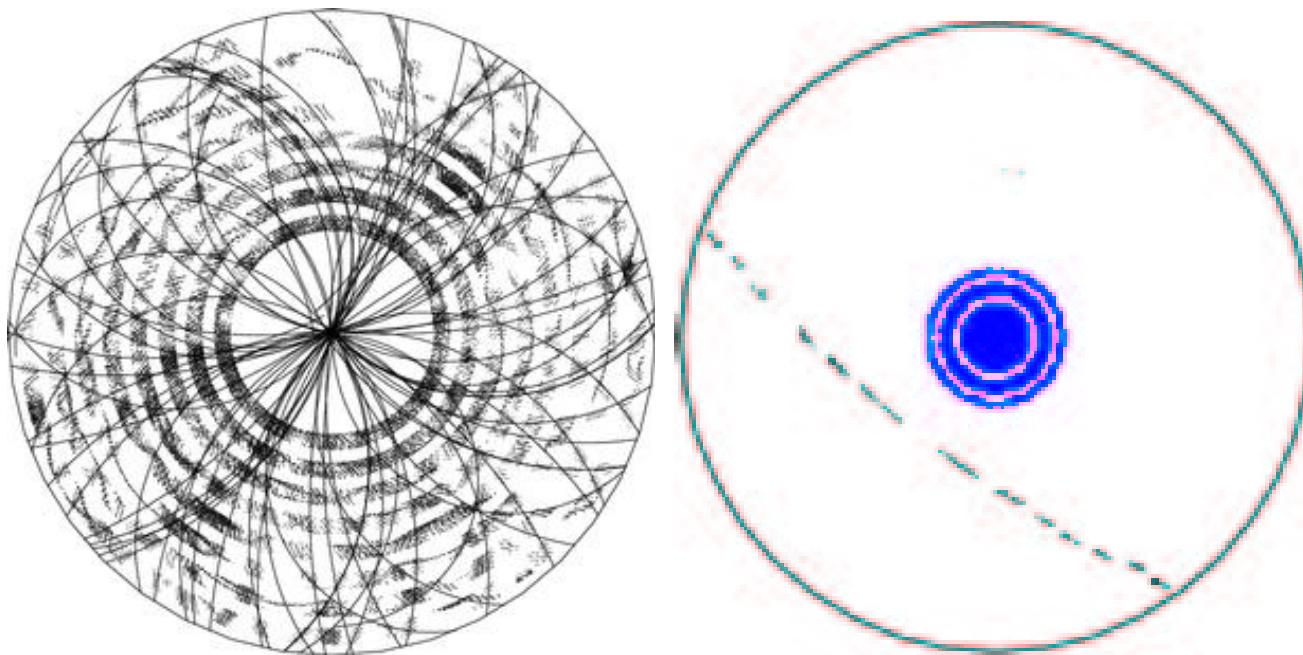
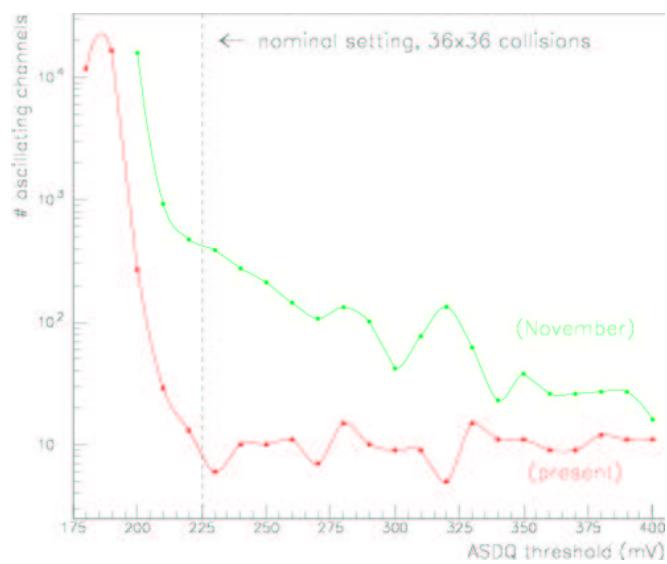
- ▷ tested during November 2000 commissioning run with partial TDC's
- ▷ fully operational for beginning of Run II, March 2001
- ▷ > 99% of channels have nominal functioning
- ▷ occasional HV tripping mitigated by disabling single sense wire
- ▷ Fall 2001: problems with failing TDC crate PS due to beam loss, fixed
- ▷ two broken wires (11/01 and 04/02) fixed within few-day accesses

COT super-cell (12 channels):

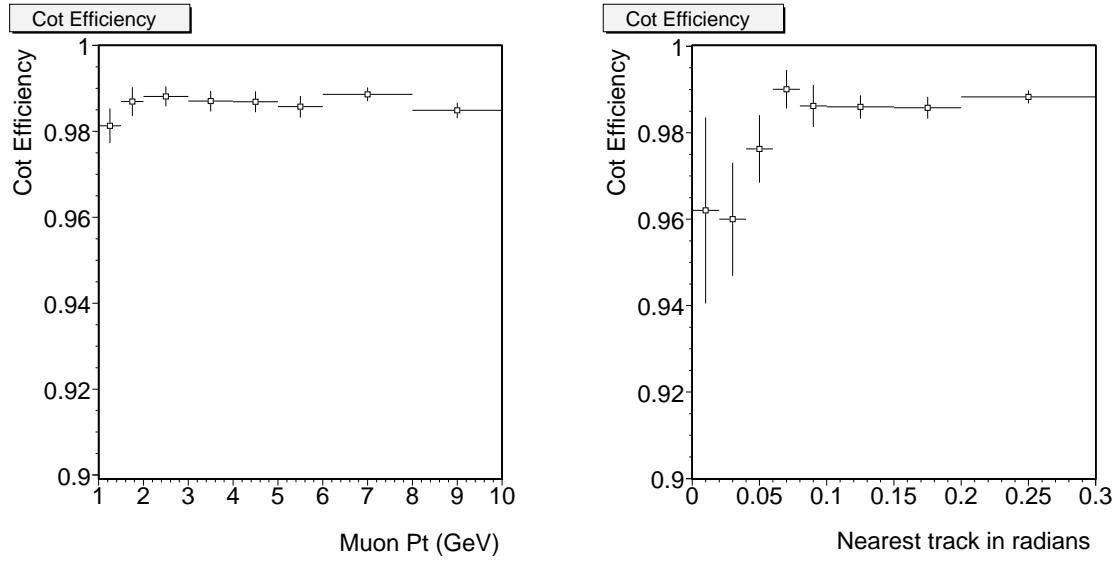


Chamber Performance: Threshold

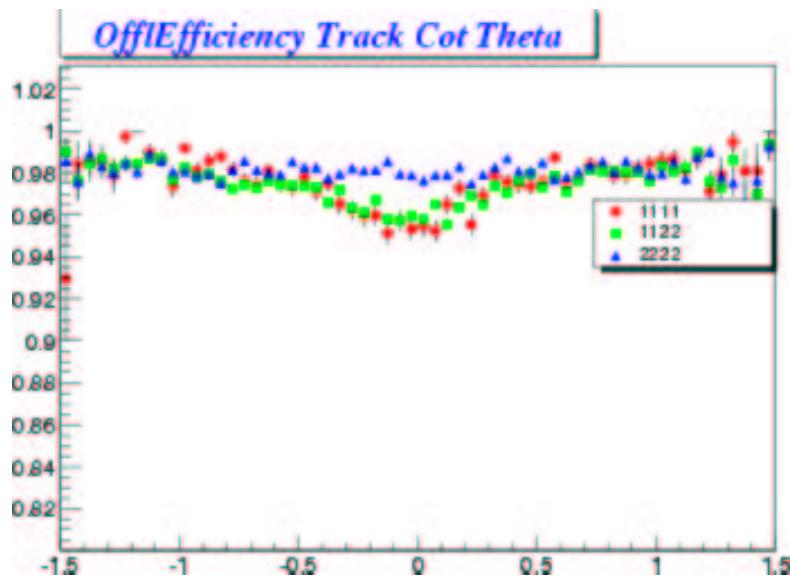
- ▷ design goal of 3 fC (~ 270 mV)
- ▷ grounding improvements to HVDB after November 2000 commissioning run
- ▷ present threshold: 2.3 fC (225 mV)



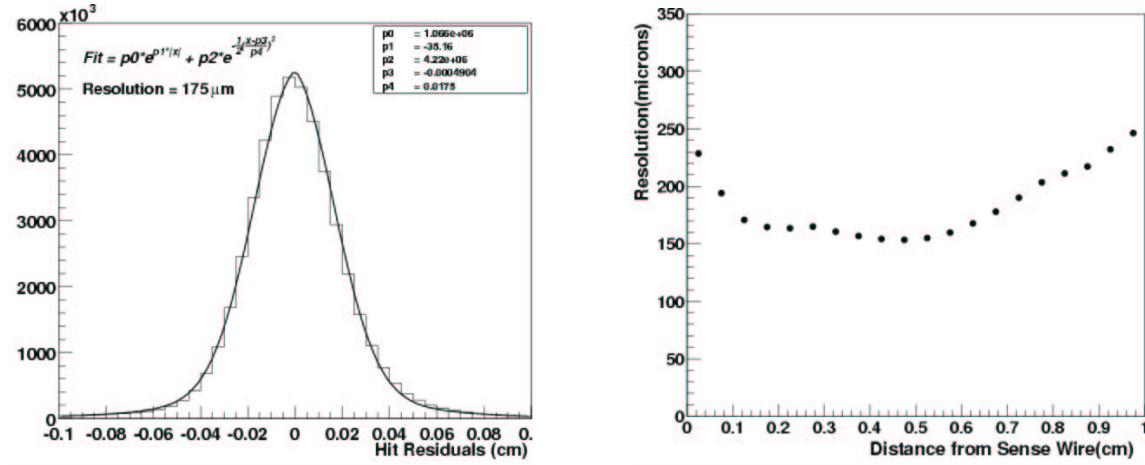
Chamber Performance: Efficiency



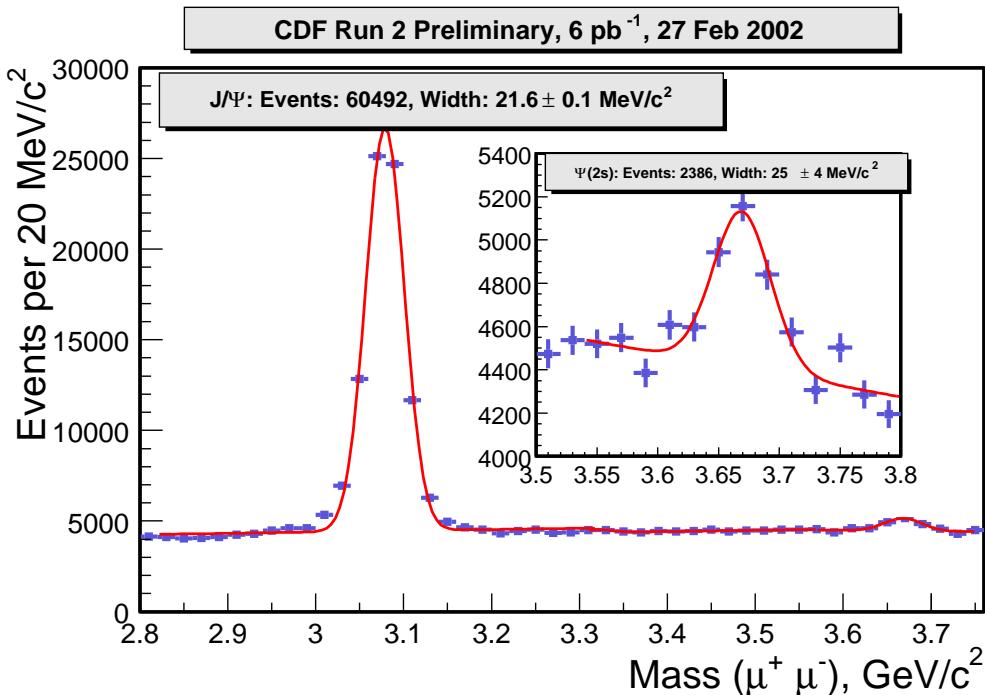
- ▷ high single-hit efficiency provides $\sim 99\%$ tracking efficiency
- ▷ uniform for track $p_T > 2 \text{ GeV}/c$, depends on track isolation
- ▷ more restrictive L1 track trigger shows drop at small η , mitigated by reducing thresholds



Chamber Performance: Resolution

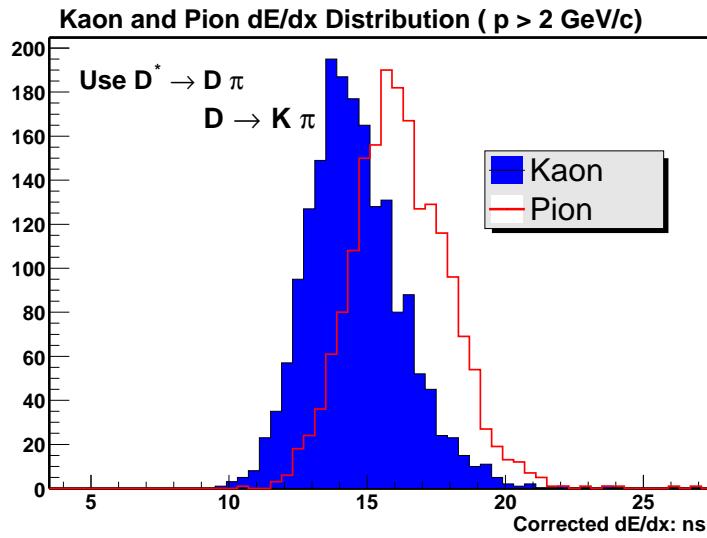


- ▷ measured COT resolution: $175 \mu\text{m}$
- ▷ meets design goal, similar to $180 \mu\text{m}$ Run I CTC
- ▷ degrades with track aspect angle, proximity to sense wire and field sheet
- ▷ providing excellent event reconstruction for Run II physics

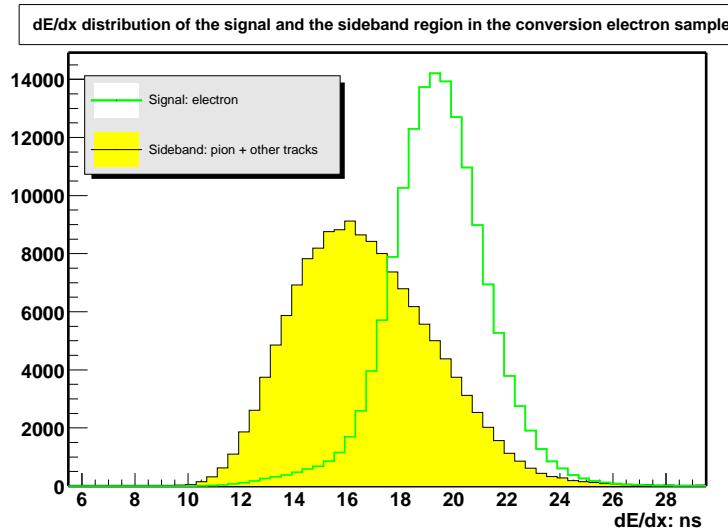


COT dE/dx measurement

- ▷ $K-\pi$ separation: 1.7 ns ($\sigma=1.6$ ns)
 - ⇒ 1- σ separation up to 10 GeV/c, decreases to 0.75- σ by 30 GeV/c



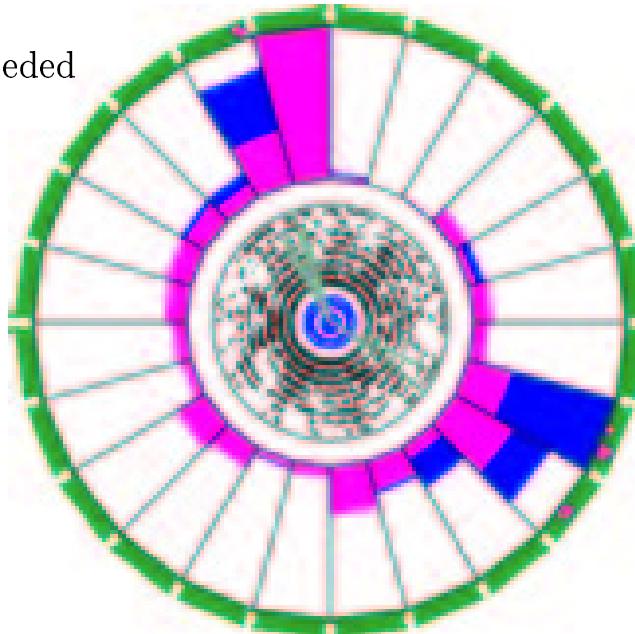
- ▷ $e-\pi$ separation:
 - ⇒ compare conversion electrons with $\Delta \cot \theta > 0.06$ sideband
 - ⇒ 2.7 ns separation ($\sigma=2$ ns) below 4 GeV/c, decreases with p



Summary and Run IIb Outlook

- ▷ the CDF COT has met or exceeded Run II design goals for:

- ⇒ discriminator threshold
- ⇒ hit position and momentum resolution
- ⇒ dE/dx separation power
- ⇒ chamber aging



- ▷ planning for Run IIb luminosities:

- ⇒ will reach eventual bottleneck with readout rate:
 - may need new VME readout scheme
 - investigating replacement TDC's using FPGA
- ⇒ handling high rates on inner superlayers:
 - “projective” geometry by deadening inner layers at large $|z|$
 - apply two-sided readout to select hits by z -position